

RQ3G100GN

Nch 40V 27A Power MOSFET

V <sub>DSS</sub>	40V
R <sub>DS(on)</sub> (Max.)	14.3mΩ
I <sub>D</sub>	±27A
P <sub>D</sub>	15W

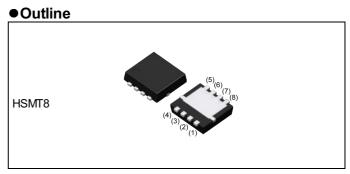
## Features

- 1) Low on resistance
- 2) High Power Package (HSMT8)
- 3) Pb-free lead plating ; RoHS compliant
- 4) Halogen Free

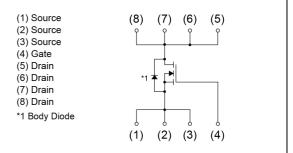
Application

Switching

5) 100% Rg and UIS tested



## ●Inner circuit



# Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	12
	Basic ordering unit (pcs)	3000
	Taping code	ТВ
	Marking	G100GN

## • Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Paramete	Symbol	Value	Unit	
Drain - Source voltage	V <sub>DSS</sub>	40	V	
Continuous dusis sument	$T_c = 25^{\circ}C$	۱ <sub>D</sub> *1	±27	А
Continuous drain current	$T_a = 25^{\circ}C$	I <sub>D</sub>	±10	А
Pulsed drain current	I <sub>DP</sub> *2	±40	Α	
Gate - Source voltage	V <sub>GSS</sub>	±20	V	
Avalanche current, single pulse	I <sub>AS</sub> *3	10	А	
Avalanche energy, single pulse	E <sub>AS</sub> *3	15	mJ	
Deurer disaination	P <sub>D</sub> <sup>*1</sup>	15	W	
Power dissipation	P <sub>D</sub> *4	2.0	W	
Junction temperature		Tj	150	°C
Operating junction and storage t	T <sub>stg</sub>	-55 to +150	°C	

## Thermal resistance

Deremeter	Sumbol	Values			Linit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *1	-	-	8.3	°C/W
Thermal resistance, junction - ambient	$R_{thJA}^{*4}$	-	-	62.5	°C/W

# • Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	Currence of	Conditions	Values			1.1	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		40	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{i}} I_{D} = 1 mA$ referenced to 25°C		26.2	-	mV/°C	
Zero gate voltage drain current	$I_{DSS}$ $V_{DS} = 40V, V_{GS} = 0V$		-	-	1	μA	
Gate - Source leakage current	le current $I_{GSS}$ $V_{GS} = \pm 20V, V_{DS} = 0V$		-	-	±100	nA	
Gate threshold voltage V <sub>GS</sub>		$V_{DS} = V_{GS}, I_D = 1mA$	1.2	-	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-4.9	-	mV/°C	
Static drain - source	<b>D</b> *5	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A	-	11.0	14.3		
on - state resistance	${\sf R}_{\sf DS(on)}^{*5}$	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10A	-	14.1	18.3	mΩ	
Gate resistance	R <sub>G</sub> f=1MHz, open drain		-	2.3	-	Ω	
Forward Transfer Admittance $ Y_{fs} ^{*5}$ $V_{DS} = 5V, I_D = 10A$		7.5	-	-	S		

\*1 T<sub>c</sub>=25°C, Limited only by maximum temperature allowed.

\*2 Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

\*3 L  $\simeq$  0.2mH, V\_{DD} = 20V, R\_G = 25 $\Omega$ , Starting T\_j = 25°C Fig.3-1,3-2

- \*4 Mounted on a Cu board (40×40×0.8mm)
- \*5 Pulsed



# •Electrical characteristics ( $T_a = 25^{\circ}C$ )

Deremeter	Cumphol	Conditions		L lucit			
Parameter	Symbol Conditions -		Min.	Тур.	Max.	Unit	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	615	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 20V	-	100	-	pF	
Reverse transfer capacitance C <sub>rs</sub>		f = 1MHz	-	28	-		
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 20V, V_{GS}$ = 10V	-	8.0	-		
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 5A	-	4.2	-		
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L \simeq 4\Omega$	-	23.1	-	ns	
Fall time	t <sub>f</sub> *5	R <sub>G</sub> = 10Ω	-	3.2	-		

# • Gate charge characteristics ( $T_a = 25^{\circ}C$ )

Deremeter	Sumbol	Conditions		Values			1 1	
Parameter	Symbol			Min.	Тур.	Max.	Unit	
Total gata charge	O *5		V <sub>GS</sub> = 10V	-	8.4	-		
Total gate charge	Q <sub>g</sub> *5	Qg°	$V_{DD} \simeq 20V$		-	4.3	-	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 10A	V <sub>GS</sub> = 4.5V	-	1.6	-	nC	
Gate - Drain charge	Q <sub>gd</sub> *5			-	1.2	-		

# •Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Deremeter	Sumbol	Conditions		Unit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	I <sub>S</sub>	T <sub>a</sub> = 25℃	-	-	1.67	А
Pulse forward current	$I_{SP}^{*2}$	$T_a = 25 C$	-	-	40	А
Forward voltage	$V_{SD}^{*5}$	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1.67A	-	-	1.2	V
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = 10A, V <sub>GS</sub> =0V	-	21	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/µs	-	12	-	nC





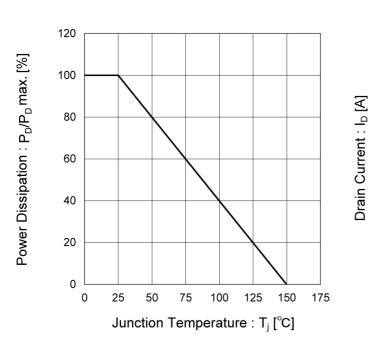


Fig.1 Power Dissipation Derating Curve

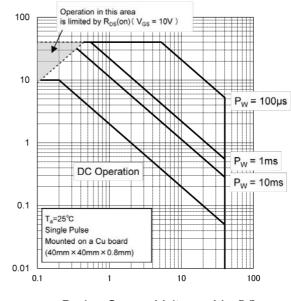


Fig.2 Maximum Safe Operating Area

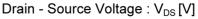
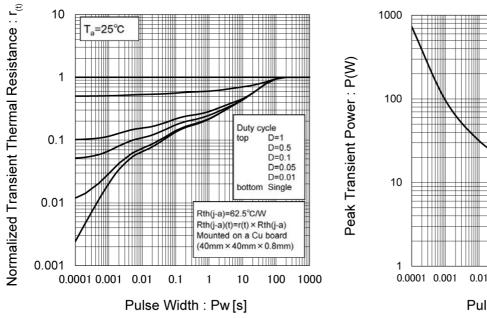
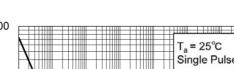
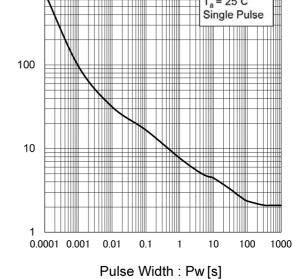


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

Fig.4 Single Pulse Maximum Power dissipation









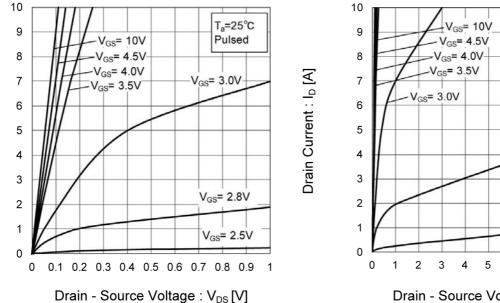
Drain Current : I<sub>D</sub> [A]

T<sub>a</sub>=25°C

Pulsed

V<sub>GS</sub>= 2.8V

V<sub>GS</sub>= 2.5V



# Fig.5 Typical Output Characteristics(I)

Fig.6 Typical Output Characteristics(II)

Drain - Source Voltage : V<sub>DS</sub> [V]

6 7 8 9 10

Fig.7 Breakdown Voltage vs. Junction Temperature

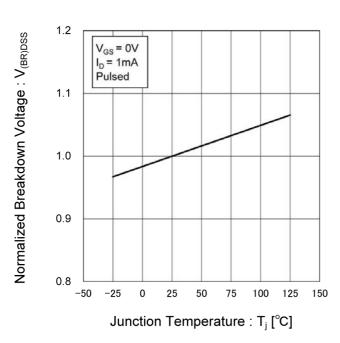
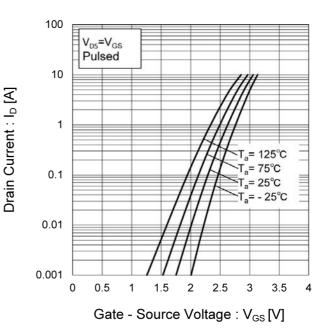


Fig.8 Typical Transfer Characteristics





# • Electrical characteristic curves

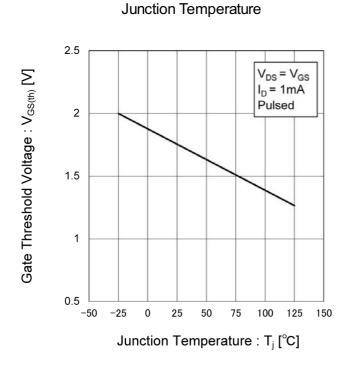


Fig.9 Gate Threshold Voltage vs.

# Fig.10 Forward Transfer Admittance vs. Drain Current

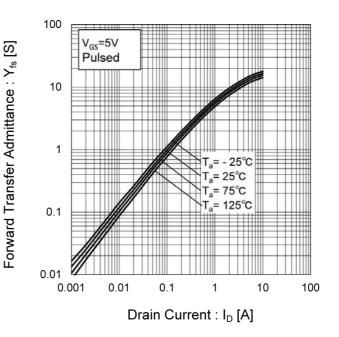
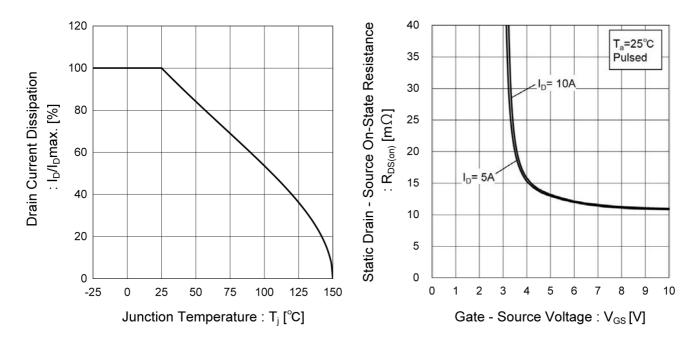
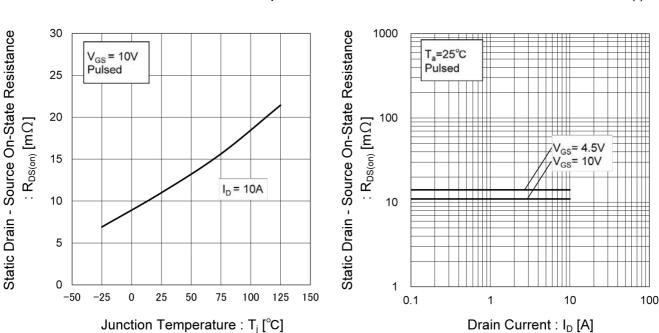


Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage







# Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

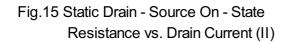
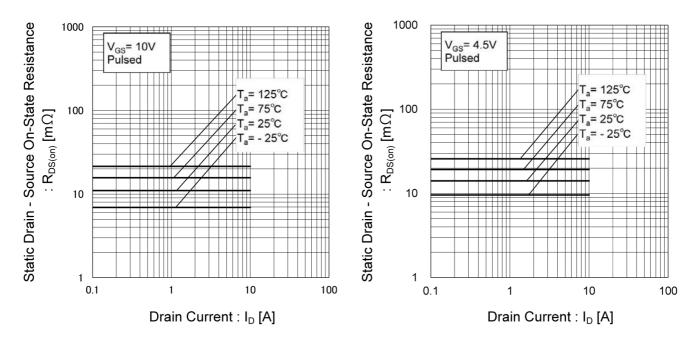


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

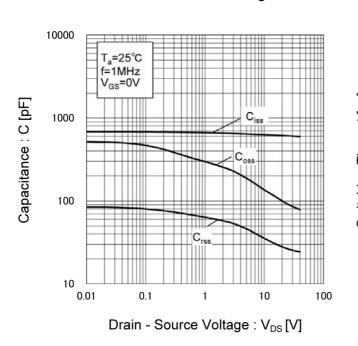




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# • Electrical characteristic curves



## Fig.17 Typical Capacitance vs. Drain - Source Voltage

Fig.18 Switching Characteristics

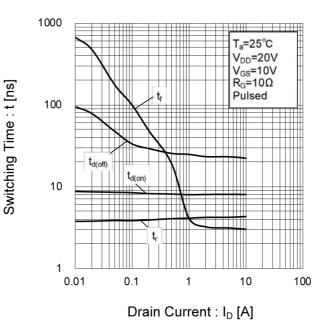


Fig.19 Dynamic Input Characteristics

Gate - Source Voltage : V<sub>GS</sub> [V]

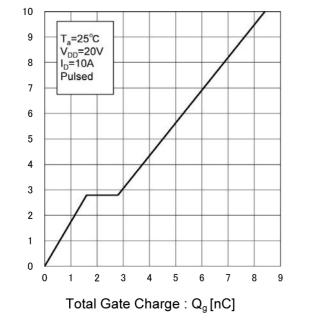
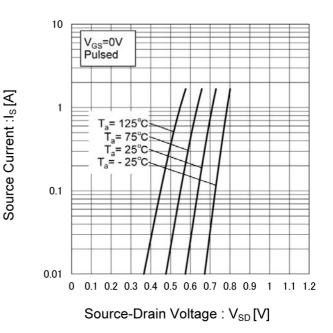


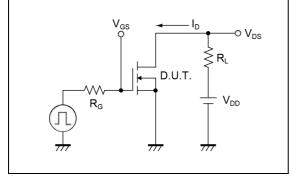
Fig.20 Source Current vs. Source Drain Voltage



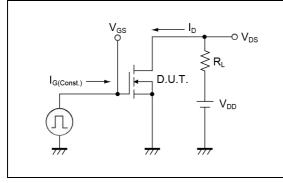


## Measurement circuits

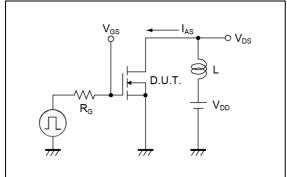
Fig.1-1 Switching Time Measurement Circuit



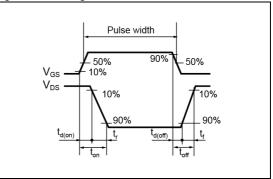
## Fig.2-1 Gate Charge Measurement Circuit



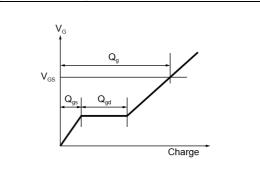
## Fig.3-1 Avalanche Measurement Circuit



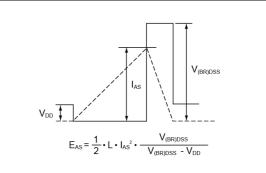
## Fig.1-2 Switching Waveforms



## Fig.2-2 Gate Charge Waveform



## Fig.3-2 Avalanche Waveform

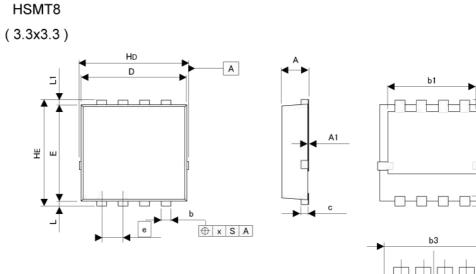


## Notice

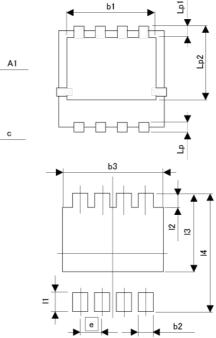
This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.



## Dimensions







Pattern of terminal position areas [Not a pattern of soldering pads]

DIM -	MILIMETERS		INC	HES
	MIN	MAX	MIN	MAX
A	0.70	0.90	0.028	0.035
A1	0.00	0.05	0.000	0.002
b	0.27	0.37	0.011	0.015
b1	2.50	2.70	0.098	0.106
с	0.10	0.30	0.004	0.012
D	3.10	3.30	0.122	0.130
E	2.90	3.10	0.114	0.122
е	0.	65	0.0	26
HD	3.20	3.40	0.126	0.134
HE	3.20	3.40	0.126	0.134
L	0.07	0.25	0.003	0.010
L1	0.07	0.25	0.003	0.010
Lp	0.20	0.40	0.008	0.016
Lp1	0.25	0.45	0.010	0.018
Lp2	2.20	2.40	0.087	0.094
x	-	0.10	-	0.004
у	(H)	0.10		0.004
	MILIME	TERS	INC	HES
	MIN	MAX	MIN	MAX
b2	14 <u>1</u> 5	0.47	i 2	0.019
b3	375	2.70		0.106
1	6 <b>a</b> i	0.50	( ¥ )	0.020
12	14 C	0.55		0.022
13	2.51	2.40	æ	0.094

Dimension in mm/inches

14

3.40



0.134

# Notice

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	CLASSⅣ	CLASSII	CLASSII	CLASSI

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  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
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  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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